### **SOFC Seals: SECA CTP Seal Meeting Overview**

(Meeting held at Sandia National Laboratory, July 8-9, 2003)

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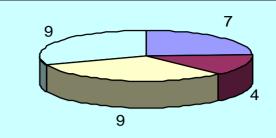
Presented at SECA Core Technology Meeting, Albany, NY Sept 30-Oct.1, 2003

### **Acknowledgements**

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• We thank Kevin Moore for facilitation at the meeting.

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Industries Universities Govt.Agencies National Labs

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### Outline

- > SECA CTP Priorities
- Seal Meeting Objectives
- > Accomplishments
- Workshop Presentations
- **Group Discussions and Story Board**
- Path Forward

### **Current Priorities:** Core Technology Program

|   |   | What                      | How   |
|---|---|---------------------------|---|
|   | 1 | Gas seals                 | <ul> <li>Glass and compressive seals</li> </ul>   |
|   | 1 | Interconnect              | <ul> <li>Modifying components in alloys</li> <li>Coatings</li> </ul>  |
|   | 2 | Modeling                  | <ul> <li>Models with electrochemistry</li> <li>Structural characterization</li> </ul>   |
|   | 2 | Cathode<br>performance    | <ul> <li>Micro structure optimization</li> <li>Mixed conduction</li> <li>Interface modification</li> </ul>  |
|   | 2 | Anode/<br>fuel processing | <ul> <li>Metal oxides with interface modification</li> <li>Catalyst surface modification</li> <li>Characterize thermodynamics/kinetics</li> </ul> |
|   | 3 | Power<br>electronics      | <ul> <li>Direct DC to AC conversion</li> <li>DC to DC design for fuel cells</li> </ul>  |
|   | 4 | Material cost             | <ul> <li>Lower cost precursor processing</li> <li>Cost model methodology</li> </ul>   |
| 3 |   |                           | Pito Poiuro, SECA Appuel Meeting, Secttle 2002     SECA 4/15/   |

### **Objective**

### Review SOFC sealing issues and requirements

### Present current status of SOFC sealing technology

- \* Seal materials
- \* Materials interactions
- \* Failure processes

### ✤ Identify

- \* Advance concepts
- \* Designs and development approaches





Obtained input from participants on new seal concepts including materials design and fabrication processes

Established consensus (via facilitated break-out sessions) on promising concepts and future R&D directions

Published results from the meeting regarding new sealing technologies

SECA CTP meeting results are available on:

http://www.seca.doe.gov

## **SOFC** Seal functions

### **SOFC** seals:

- Prevent mixing of fuel and oxidant within a cell stack
- Prevent leaking of fuel and oxidant from stack
- Electrically isolate cells in stack
- May provide mechanical bonding of cell components

## Seal Requirements

| Functional requirements and materials selection parameters |  |  |  |  |  |
|--|--|--|--|--|--|
| Mechanical   | <ul> <li>Hermetic (or near hermetic)</li> <li>Minimal CTE mismatch (or ability to yield or deform to mitigate<br/>CTE mismatch stresses)</li> <li>Acceptable bonding strength (or deformation under compressive<br/>loading)</li> <li>Thermal cycle stability</li> <li>Vibration and shock resistance (for mobile applications)</li> </ul> |  |  |  |  |
| Chemical   | <ul> <li>Long-term chemical stability under simultaneous oxidizing/wet<br/>fuel environments</li> <li>Long-term chemical compatibility with respect to the adjacent<br/>sealing surface materials</li> <li>Resistance to hydrogen embrittlement/corrosion</li> </ul>   |  |  |  |  |
| Electrical   | Non-conductive   |  |  |  |  |
| Fabrication  | <ul> <li>Low cost</li> <li>High reliability with respect to forming a hermetic seal</li> <li>Sealing conditions compatible with other stack components</li> </ul>  |  |  |  |  |

### **Technology Status**

Rigid seals – most mature, easy to fabricate but require CTE match, chemical stability

Compressive seals – promising with respect to CTE but limited development, requires external load frame

Cross cutting tools –

Computational tools – available to study various failure modes during steady state and thermal cyclic conditions

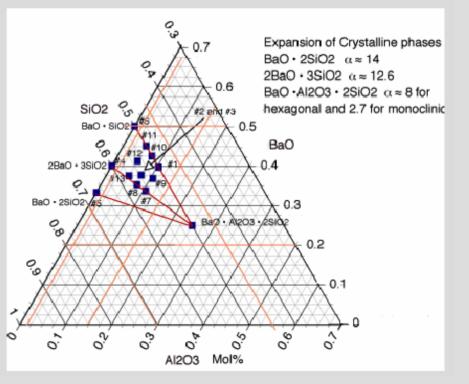
Other experimental tools - characterization, mechanical and chemical behavior

## Rigid glass seals

### BaO-Al<sub>2</sub>O<sub>3</sub>-SiO<sub>2</sub> Seals

• AI-Si-X( Alkaline) system

- CTE tailored
- Porosity formation
- Interaction with scales



### Brazed metal seals

- Potential alternative to glass-based seals
- Involves use of molten filler metal which flows and fills gap between components
- Pros:
  - Wetting behavior of molten metal facilitates hermetic sealing
  - Easy to fabricate
  - Properties can be tailored (CTE, T<sub>m</sub>)

Cons:

- Electrically conductive!
- Few systems compatible with sealing under oxidizing conditions
  - Noble metal brazes expensive
  - Ag relatively inexpensive, but is unstable in dual environment

## Compressive seals

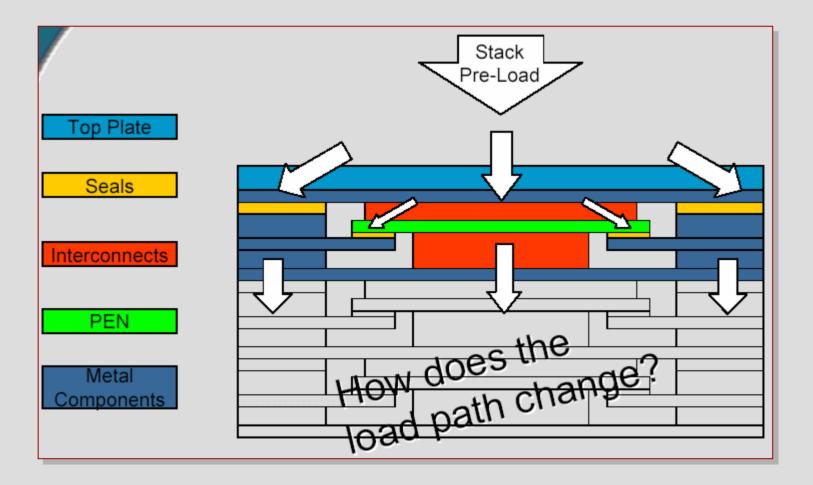
### Pros:

- May provide mechanical "de-coupling" of adjacent stack components (avoid thermal stress development during fabrication, operation, thermal cycling)
- Potentially easy to fabricate
- In simplest form, no viscous/liquid sealing step required

#### Cons:

- Potential for high leak rates through seal/component interfaces for simple gasket approaches
- Few stable, compliant, hermetic candidate materials
- Load frame required to maintain compressive stress
  - Adds expense, complexity
  - Effect of long-term compressive load on dimensional stability of other stack components?

## Seal designs





- What are the PEN stresses as a function of boundary stiffness during steady state or transient conditions?
- What are the cell edge displacements as a function of PEN stresses?
- What are the effects of stack B.C.s on stresses?
- What is the state of stress and displacement in the seal area?
- How does a dead load distributes throughout the stack, especially sealing areas?

### **SBIR Seal Development Activities**

#### Phase I Conclusions

- MEXTECH
- Highly Textured Seal Materials Result from Tape Casting Process
- Green Tapes Amenable to Many Geometries
  - Gasket Approach Can Be Tailored
  - Thickness Controlled Through Lamination
- Seal Performance Controlled by Composition
  - Crystalline Phase: TCE, Mechanical Strength
  - · Glass Content, Properties: Wetting, Stability
  - Binder Content

#### Summary

- >Several candidate materials and methods exist for sealing SOFCs.
- These materials and methods must be tailored to the devices and applications.
- A balance of material properties is required for an effective seal.
- > Device design can be used to influence seal requirements.
- Pyrolysis of preceramic polymer precursors offers a promising method for sealing SOFCs, further study is required.
- Further modeling, materials testing, design evaluation, and adoption of standards are strongly recommended.

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# Technical approach



- Fundamental gaps
- Engineering needs

## **Technical Challenges**

| RIGID CHEMICAL  | SLIDING MECHANICAL   | COMPLIANT WET   |
|---|--|---|
| Glass - Pros<br>• Lowest leakage<br>• Inexpensive<br>• Glasses not limited to stoichmetric<br>• Excellent thermal and environmental stability<br>• Processing flexibility (automatable) in-<br>expensive<br>• Successful experience "short-term"<br>Glass - Cons<br>• Constrains cell movement during thermal<br>excursions<br>• Accommodation of CTE mismatch<br>• Increases strength requirement on PEN<br>• Increases tendency for cracking<br>• Metal to ceramic delamination<br>• Different materials thermal capacitance<br>• compositions (tailorable)<br>• Application temperature<br>• Migration of species<br>• Assembly tolerances and compensation<br>• Seal/cell surface debonding, cell component<br>debonding, interface stream<br>• Durometer u/mils<br>• Increases time of heating and cooling<br>(fabrication)<br>• Changing material structure with cycling<br>Cements<br>• Con: CTE – coefficient thermal expansion<br>• Pro: No requires loading<br>Organo precursor cements - Cons<br>• Steam?<br>• CTE mismatch<br>• Porosity or density<br>• Hydrogen<br>Nonconductive braze system<br>All - Con<br>• Interfacial reactivity | Pros Tolerance for CTE mismatch Less demanding on strength of cell Easier to disassemble - repairable Cons Requires pressure Surface preparation & finish Limitations on location for usage Larger mechanical structure + seal volume Leak rate degradation (cycling) Degradation & seal material (corrosion) Creep wear/products others Problems with external loads in plane of cells Electrical insulation for metallic seals Stacking issues & assembly Operational procedure Stack height dimensional changes & long-term operation How big of load needed and applied Need for flexibility to seal YSZ variations Dimensional tolerance Compliance vs. spring back | Pros <ul> <li>Allows CTE mismatch</li> <li>Potential for low leakage</li> <li>Accommodate irregularities in surface</li> <li>Low interfacial stresses</li> <li>Self-healing</li> </ul> Cons <ul> <li>Molten glass - voltalization</li> <li>Molten glass - continuous change in properties</li> <li>Need for reservoir to replenish</li> <li>Possible wicking</li> <li>What liquid?</li> <li>Reactivity</li> <li>Possibility of migration and lead formation</li> <li>Containment stop</li> <li>Proper viscosity over operational temperature range</li> </ul> |

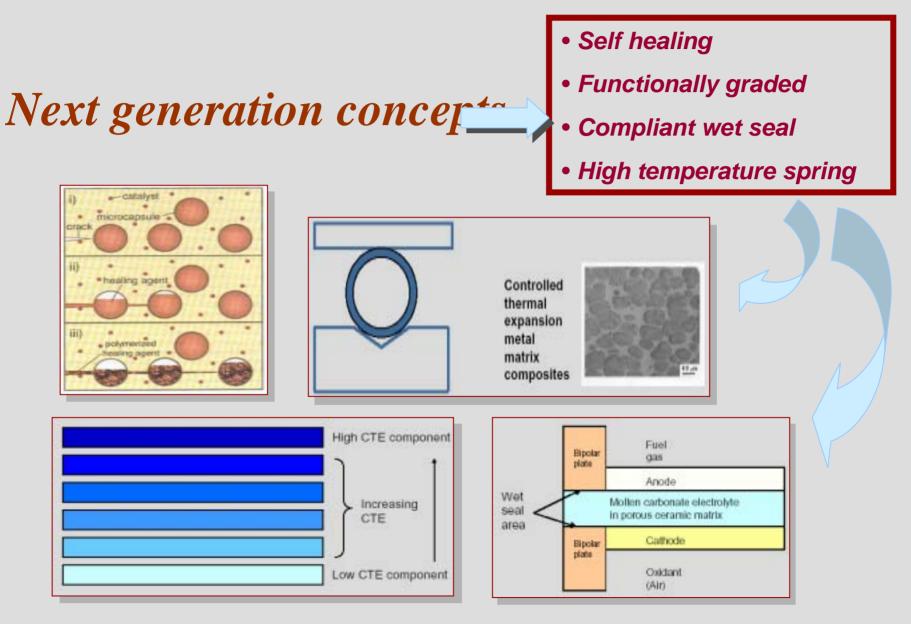
## **Technical Challenges**

#### TABLE 1.2 NOVEL R&D APPROACHES PLUS REQUIREMENTS

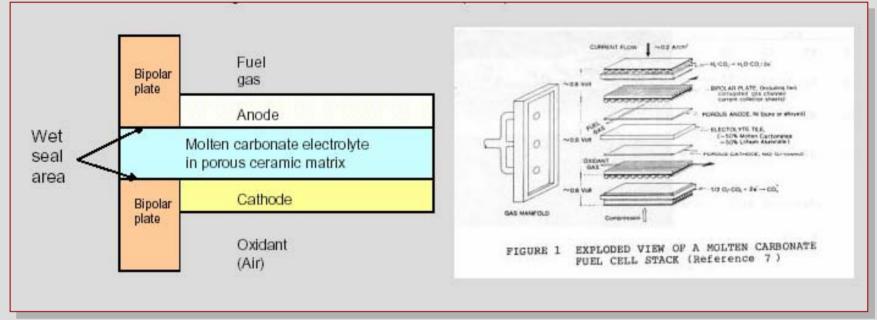
| COMPLIANT WET  | Rigid  | SMART MATERIALS   | GRADED SEAL<br>STRUCTURES  | FLEXIBLE<br>Mechanical Seals   | REQUIREMENTS  |
|--|--|---|--|--|---|
| <ul> <li>Impregnated<br/>materials, e.g., felt,<br/>fabric</li> <li>Self-healing materials</li> <li>Porous/dense<br/>reservoir/hard stop<br/>wet seal</li> </ul> | <ul> <li>Microcracking<br/>toughened glasses</li> <li>Particle reinforced<br/>glasses</li> <li>Development of<br/>organo precursors</li> </ul> | <ul> <li>Adaptive</li> <li>Magneto strictive</li> <li>Electro rheologic<br/>material</li> <li>Piezo electric</li> <li>SMA - shape<br/>memory alloys</li> <li>"MEMS" inspired<br/>manufacturing<br/>approach</li> <li>Magneto-elastic<br/>materials</li> </ul> | <ul> <li>Multi-layered/Graded<br/>microstructures, e.g.,<br/>porosity, nested Vs</li> <li>Chemical<br/>modification of mica</li> <li>Multi- functional<br/>layered structure</li> <li>Engineered<br/>materials, e.g.,<br/>macor</li> </ul> | <ul> <li>Zr O-ring</li> <li>Compliance with<br/>rigid tubes 3YSZ</li> <li>Glass coated belows</li> <li>High temperature<br/>RTV</li> <li>Nano ceramic<br/>springs</li> </ul> | <ul> <li>Voltage effects on seal</li> <li>Standardized testing protocols</li> <li>Strain management</li> <li>Seal design methodology</li> </ul> |

| Sealing Concepts                       | Leak<br>Tightness | Stability -<br>Mechanical | Stability -<br>Chemical | Manufactur<br>ability | Cyclic<br>Ability | Afford ability | Rating | Technology<br>Readiness E/D/R |
|--|-------------------|---------------------------|-------------------------|-----------------------|-------------------|----------------|--------|-------------------------------|
| Particle Reinforced                    | 7.0               | 5.9                       | 5,8                     | 7.2                   | 4.6               | 7.2            | 37.7   | D                             |
| Glasses                                | 7.0               | 5.9                       | 5.6                     | 1.2                   | 4.0               | 1.2            | 51.1   | U                             |
| Impreganted Materials<br>Felt/Fabric   | 6.0               | 6.6                       | 5.6                     | 6.5                   | 5.9               | 5.5            | 36.1   | R-D                           |
| Micro-Crack Toughened<br>Glasses       | 6.6               | 5.2                       | 6.2                     | 6.7                   | 4.4               | 6.8            | 35.9   | D                             |
| Organo-precursors                      | 7.4               | 5.9                       | 5.3                     | 6.8                   | 4.2               | 5.4            | 34.9   | R-D                           |
| ZR O-ring                              | 3.8               | 6.7                       | 7.8                     | 5.1                   | 6.2               | 4.6            | 34.2   | R-D                           |
| Porous-Dense Reservoir<br>Wet Seal     | 6.1               | 5.6                       | 4.1                     | 5.6                   | 6.5               | 6.1            | 33.9   | R-D                           |
| Glass Coated Bellows                   | 7.0               | 6.5                       | 6.0                     | 4.2                   | 6.3               | 3.3            | 33.3   | R-D                           |
| Multi-Layered/ Graded<br>Materials     | 6.4               | 6.8                       | 5.1                     | 4.2                   | 6.3               | 4.4            | 33.2   | R-D                           |
| Self-Healing Materials                 | 6.4               | 6.4                       | 4.9                     | 4.0                   | 6.8               | 4.7            | 33.2   | R                             |
| Chemical Mods to Mica                  | 4.8               | 5.4                       | 5.9                     | 5.0                   | 5.6               | 5.5            | 32.3   | R-D                           |
| Engineered Materials                   | 6.0               | 5.6                       | 5.4                     | 4.3                   | 5.4               | 4.5            | 31.3   | R-D                           |
| Multi-Functional Layered<br>Structures | 6.2               | 6.2                       | 5.6                     | 3.9                   | 5.1               | 3.4            | 30.4   | R                             |
| Shape Memory Materials                 | 5.0               | 5.0                       | 5.1                     | 5.0                   | 6.0               | 3.7            | 29.8   | R                             |
| Complaince w/Rigid Tubes               | 4.1               | 5.8                       | 5.8                     | 4.1                   | 5.3               | 4.1            | 29.1   | R-D                           |
| Hi-Temp RTV                            | 7.4               | 6.4                       | 4.1                     | 3.1                   | 5.2               | 2.6            | 28.8   | R                             |
| Adaptive Materials                     | 6.3               | 4.6                       | 4.0                     | 2.9                   | 5.0               | 3.5            | 26.4   | R                             |
| Nano Ceramic Spring                    | 4.5               | 5.3                       | 6.3                     | 2.8                   | 5.5               | 2.0            | 26.4   | R                             |
| Piezo Electric Materials               | 3.8               | 5.2                       | 4.0                     | 4.2                   | 5.0               | 3.4            | 25.6   | R                             |
| MEMS                                   | 4.5               | 5.3                       | 4.5                     | 3.1                   | 5.4               | 2.3            | 25.1   | R                             |
| Magneto-Elastic Materials              | 3.8               | 4.5                       | 4.7                     | 4.0                   | 5.0               | 2.8            | 24.7   | R                             |
| Electro-Rheologic<br>Materials         | 4.6               | 5.0                       | 3.2                     | 3.4                   | 4.4               | 3.4            | 24.1   | R                             |
| Magneto-Restrictive<br>Materials       | 3.1               | 2.3                       | 1.8                     | 1.7                   | 1.9               | 1.6            | 12.5   | R                             |

#### SECA Core Technology Task Force on Sealing Rating of Sealing Concepts



## **Compliant Molten Seals**



At operating temperature, seal is liquid (highly viscous or contained in porous matrix by surface tension).

At low temperatures, seal solidifies, but is non-bonding, allowing for sliding to prevent stress buildup

Utilized in Molten Carbonate Fuel Cells (600-700°C)

Singh et al., Corrosion 87, NACE (1987).

## **Technical Challenges**

### Development Needs

- Identify or develop suitable liquids
- Determine surface energies
- Temp/ viscosity relationships
- Evaporation rates
- Reservoir microstructure
- Manufacturability method of surface treatment – control microstructure
- Identify surface treatments wetability
- Dielectric properties



- Microstructure
- Surface Treatments
- Temp/ viscosity relations
- Evaporation rates



**Based on the findings from the CTP seal meeting, we initiated:** 

- Seal development program at Sandia National Laboratory
- Collaboration with NASA

• More emphasis on seal development activities within PNNL-Core Technology Program

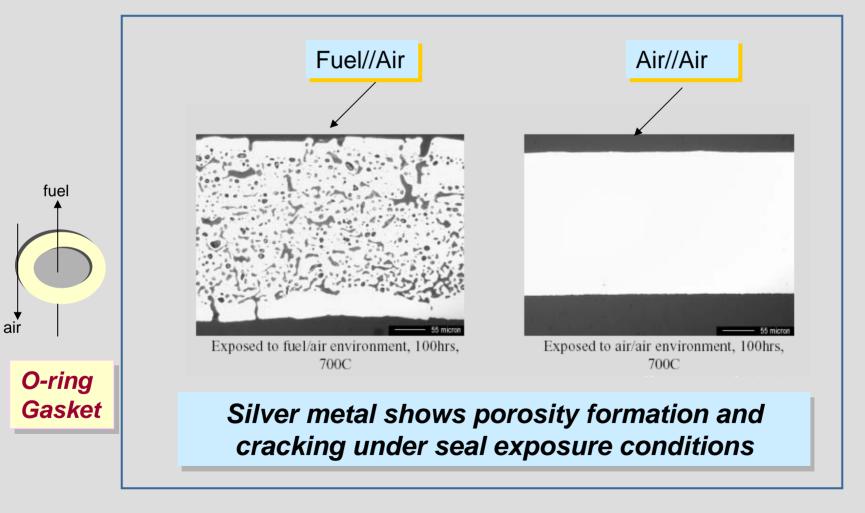


Based on the availability of funds, we plan to initiate seal development projects through solicitations.

We seek specific ideas and white papers on broad areas identified in workshop report.

We encourage you to review results from the web site





# Seal Development Approach

